

CAREER SNAPSHOT

Kyung Wook Park — Senior Semiconductor Expert

Nearly 3 decades — Tape-Out • EDA • Sales • Physical Design • Verification • IC Design

Munich, Germany

DAUERAUFENTHALT-EU

TECHNICAL EXPERTISE

- Design-to-Mask & Tape-Out: OPC/RET, MDP, mask assembly, Manufacturing, 300mm fab integration (Bosch)
- Physical Verification (Calibre): DRC | LVS | PERC | OPC RET | SmartFILL | DFM | Pattern Matching
- Memory & Mixed-Signal: DDR1/DDR2, arrays, decoders, I/O, Sense Amps, ESD/LUP
- Advanced Processes: TSMC N3E/N7/N16/N28 | GF 45/28/22 | Intel i1277/i1226 | Samsung 14nm
- EDA & Automation: Siemens Calibre, Cadence, Pegasus, SKILL, Synopsys, ICC2, Python, and TCL

CUSTOMER & BUSINESS IMPACT

- Siemens EDA (Calibre CAE): customer support, training, adoption (Intel, GF, Infineon, Apple, and ST)
- ELMOS: Senior Sales Manager Asia, €15M revenue ownership
- DSP-Weuffen: China/Korea market development for ADAS SoCs
- Cross-functional leadership across Sales, Product, Design, QA, Finance, and Legal teams
- Secured key accounts and led successful annual price negotiations, maintaining and growing revenue stream

ACHIEVEMENTS & RECOGNITION

- Patents: 2 US + 12 Korean (DRAM & design automation)
- Awards: Key Talent Award (€20,000), Outstanding Achievement, Best Product
- Recognized expert in Memory, CAD EDA, DFM, SmartFILL, OPC, PERC and DRC

GLOBAL EXPERIENCE & CORE STRENGTHS

- Germany, Korea, Taiwan, China, Japan, Singapore — EMEA/APAC engagements
- Languages: English (C2), Korean (native), German (B2)
- Core strengths: End-to-End lifecycle, Automation, and Problem-solving